

Flux LP1

Versatile, chloride-free, and moderately active product designed for precise soldering of SMD components. It is ideal for dual solder wave applications, ensuring excellent wetting, adhesion, and aesthetically pleasing joints. Thanks to its formula based on an alcoholic solution of organic compounds, Flux LP1 guarantees durability, safety, and reliability in a wide range of industrial applications.

Product features:

- ✓ excellent wetting and minimization of solder bridges,
- ✓ chloride-free formula with no risk of corrosion,
- ✓ low solids content (~4%),
- ✓ compliant with ISO 9454 type 2233 and J-STD-004 ORLO standards,
- ✓ No Clean – no need to remove residues after soldering.

Applications:

- ✓ SMD soldering using dual solder wave,
- ✓ precise soldering of electronic components.

Physicochemical properties

Appearance	Slightly straw-colored liquid
Odor	Sharp, alcoholic
Density at 20°C	0.80 g/cm ³
Viscosity at 20°C	14.7 cP
pH (1% aqueous solution)	3.34
Water solubility	Partial with sediment formation
Content of non-volatile substances	min. 4%
Specific cross resistance (ASTM D1169)	1.0*10 ⁻⁴ p _v Ω x m 1.0*10 ⁻⁶ Ω x cm
Shelf life	3 years



Compatibility:

Flux LP1 is safe for electronic components and eliminates the risk of corrosion, even during long-term use. Its formula ensures cleanliness and durability of connections in various applications.

Application method	
Bottle	Yes
Brush	Yes
Flux wave	Yes
Flux foam	Yes
Flux spraying	Yes
Flux immersion	Yes

Usage instructions:

Restricted to professional users. Read safety data sheet carefully prior to use.

Before use, make sure the surface is clean and dry. Apply the flux using the selected method—foam, spray, immersion, or with a brush—depending on the project requirements. Proceed with soldering using a dual solder wave. The product does not require cleaning after the soldering process, saving time and ensuring convenience.

In case of interruptions in the operation of flux dispensing devices, we recommend periodically flushing the system with Alcohol PCB Cleaner. This agent removes dried No Clean flux residues more effectively than isopropyl alcohol, preventing nozzle clogging and maintaining process stability.

Package	
Bottle with brush	100 ml (ART.AGT-041) - 8 pcs.*
Bottle	500 ml (ART.AGT-073) - 1 pc.* 1 l (ART.AGT-074) - 1/4 pcs.*

*Quantity of pcs. in a bulk package.

Storage:

Store the material in plastic containers (e.g., made of HDPE, PP, or PVC). Containers must be kept tightly closed in a dry, ventilated area, out of reach of children, at a temperature of 5–25°C. Do not store together with oxidizing substances.

Technical support:

AG TermoPasty provides technical support, answering questions about the technical specifications and applications of our products. Please contact us via email at info@termopasty.pl.

Note:

The data presented in this document reflect our current state of knowledge and describe the typical properties and applications of the product. However, the responsibility for determining the suitability of this product for specific applications lies with the user. AG TermoPasty is not liable for the results of the product's use, as the conditions of its application are beyond our control.

